

DESIGN OPTIMIZATION OF BUTTON-TYPE BPM ELECTRODE FOR THE SPRING-8 UPGRADE



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Abstract

The design of a button-type BPM electrode for the SPRING-8 upgrade has been optimized from the perspectives of **1) mechanical structure, 2) rf characteristics, and 3) thermal issue**. We have adopted the electrode structure without a sleeve enclosing a button to maximize the button diameter. To minimize the beam impedance and the trapped mode heating of the electrode, the rf structure has been optimized by 3D electro-magnetic simulations. The reduction of the heating suppresses thermal deformation of the electrode and the BPM block, and improves thermal stability of the BPM system. The mechanical tolerance of the electrode was defined to fit the error budget for the total BPM offset error of 100 μm rms.

Required Performances for the BPM system

- 1) Resolution**
 - Single-Pass (SP) mode 100 μm rms @100 pC single bunch
 - COD mode 0.1 μm rms @100 mA 1kHz b.w.
- 2) Accuracy**
 - Single-Pass (SP) mode 100 μm rms ($\pm 200 \mu\text{m}$ max.) before BBA
 - COD mode 10 μm rms after BBA
- 3) Stability**
 - Drift of BPM offset < 5 μm /month

Points of the BPM electrode design

- 1) Maximization of the signal intensity** to satisfy the required Single-Pass resolution (100 μm rms)
- 2) Mechanical tolerance** to fit the error budget of the allowable BPM offset (100 μm rms)
- 3) Minimization of the trapped mode heating** to reduce the drift due to the thermal deformation

Button diameter

Maximization to obtain sufficient signal intensity

Button-type Electrode :

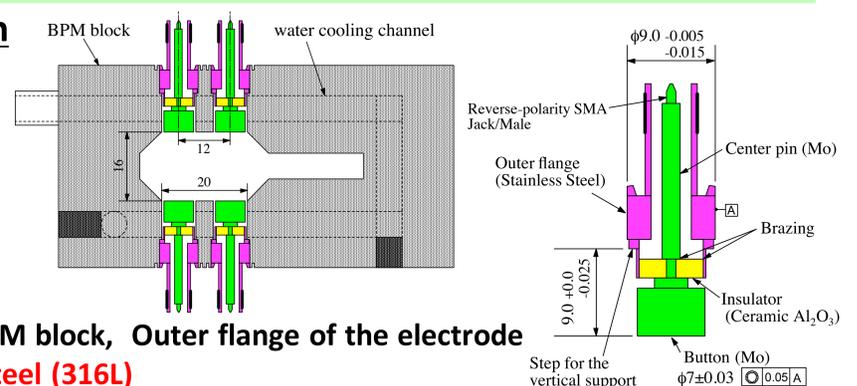
- Mounted with the narrow horizontal span of 12 mm.
- Structure without the sleeve enclosing the button.

Maximized Button diameter is $\phi 7 \text{ mm}$.

Mechanical Tolerances

- Button diameter $\pm 30 \mu\text{m}$
- Vertical button position
 - > 50 μm as an offset back into the housing hole
- Horizontal button position
 - > Centricity of 50 μm between the button and the outer flange

Mechanical Design



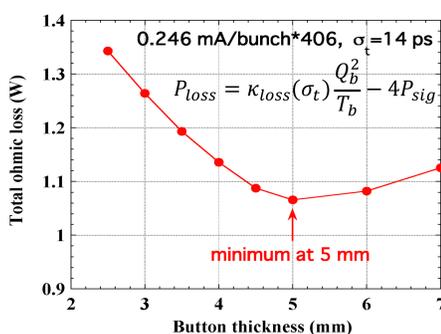
Materials

- Water-cooled BPM block, Outer flange of the electrode -> **Stainless steel (316L)**
- Button and center pin -> **Molybdenum (Mo)**
 - Suppression of the trapped mode heating
 - Mo: High electric and thermal conductivity
- Insulator -> **Alumina ceramic (Al₂O₃)**
 - Thermal conductivity 18 W/m/K close to that of stainless steel

RF and Thermal Simulations

Ohmic Loss Minimization and Trapped Modes Analysis

- Trapped resonance modes lead to the heating and beam impedance.
- Main resonance modes excited in a gap between button and housing hole.
- Narrowing the gap simply reduces the resonance strength.
 - > It requires tighter machining tolerance to avoid electric short.
- We selected the same gap of 0.5 mm as the electrode of the present SPRING-8.
- Button thickness 5mm was optimized to minimize the total ohmic loss P_{loss} .



Assumed bunch fill pattern of **0.25 mA/bunch*406** gave the maximum heat load among the equally spaced bunch fill patterns for a total stored current of 100 mA. Bunch lengthening due to potential well distortion was taken into account. The bunch length s_t is 14 ps for the bunch current of 0.25 mA.

Signal Intensity

$$\text{Required signal voltage } V > \frac{k_{x,y}}{2\sigma_{resol}} \sigma_v$$

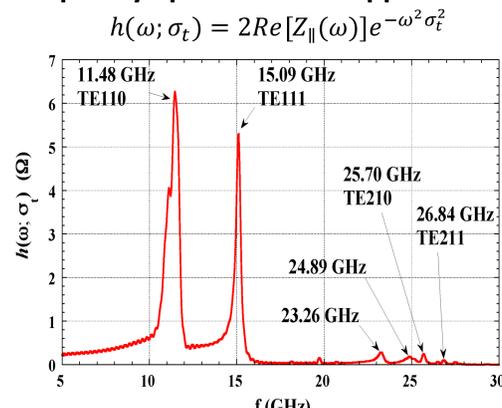
➔ 0.38 mV -> -55 dBm

Sensitivity coefficients : $k_x = 6.8 \text{ mm}$, $k_y = 7.7 \text{ mm}$
 Demanded resolution : $\sigma_{resol} = 100 \mu\text{m}$ (rms)

Equivalent input noise power :
 -87 dBm ($\sigma_v = 10 \mu\text{V}$)
 Thermal -101 dBm
 NF of BPM electronics including cable loss 14 dB

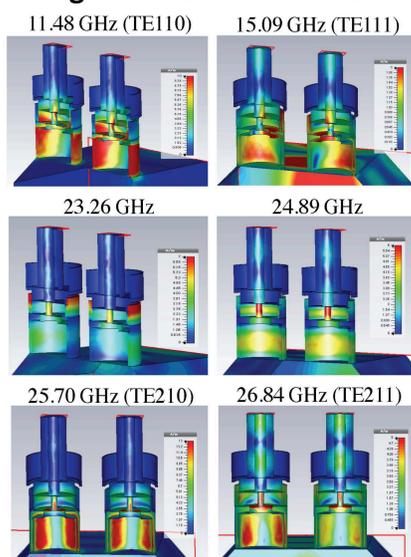


Frequency spectrum of trapped modes



$$\text{Loss factor } \kappa_{loss}(\sigma_t) = \frac{1}{2\pi} \int_0^\infty h(\omega; \sigma_t) d\omega$$

Magnetic field distributions



Heating of the BPM Electrode and the Block

- For a temporary bunch filling pattern: 0.25 mA/bunch*406 @Total current 100 mA, bunch length 14 ps (rms)
- The total heat input to the whole of the BPM head -> 1.1 W
- Estimation of heat input to the button surface, center pin and the inside of housing hole.
- We computed a temperature distribution of the BPM head.

Heat input condition

